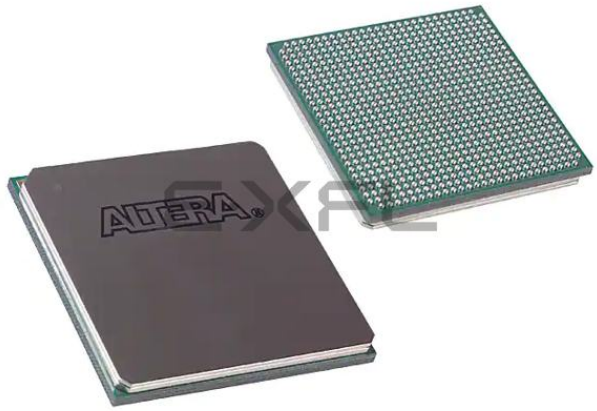


Welcome to E-XFL.COM

Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Active
Number of LABs/CLBs	7155
Number of Logic Elements/Cells	114480
Total RAM Bits	3981312
Number of I/O	528
Number of Gates	-
Voltage - Supply	1.15V ~ 1.25V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	780-BGA
Supplier Device Package	780-FBGA (29x29)
Purchase URL	https://www.e-xfl.com/product-detail/intel/ep4ce115f29c7

Chapter Revision Dates

The chapters in this document, Cyclone IV Device Handbook,, were revised on the following dates. Where chapters or groups of chapters are available separately, part numbers are listed.

Chapter 1. Cyclone IV FPGA Device Family Overview
Revised: *March 2016*
Part Number: *CYIV-51001-2.0*

Chapter 2. Logic Elements and Logic Array Blocks in Cyclone IV Devices
Revised: *November 2009*
Part Number: *CYIV-51002-1.0*

Chapter 3. Memory Blocks in Cyclone IV Devices
Revised: *November 2011*
Part Number: *CYIV-51003-1.1*

Chapter 4. Embedded Multipliers in Cyclone IV Devices
Revised: *February 2010*
Part Number: *CYIV-51004-1.1*

Chapter 5. Clock Networks and PLLs in Cyclone IV Devices
Revised: *October 2012*
Part Number: *CYIV-51005-2.4*

Chapter 6. I/O Features in Cyclone IV Devices
Revised: *March 2016*
Part Number: *CYIV-51006-2.7*

Chapter 7. External Memory Interfaces in Cyclone IV Devices
Revised: *March 2016*
Part Number: *CYIV-51007-2.6*

Chapter 8. Configuration and Remote System Upgrades in Cyclone IV Devices
Revised: *May 2013*
Part Number: *CYIV-51008-1.7*

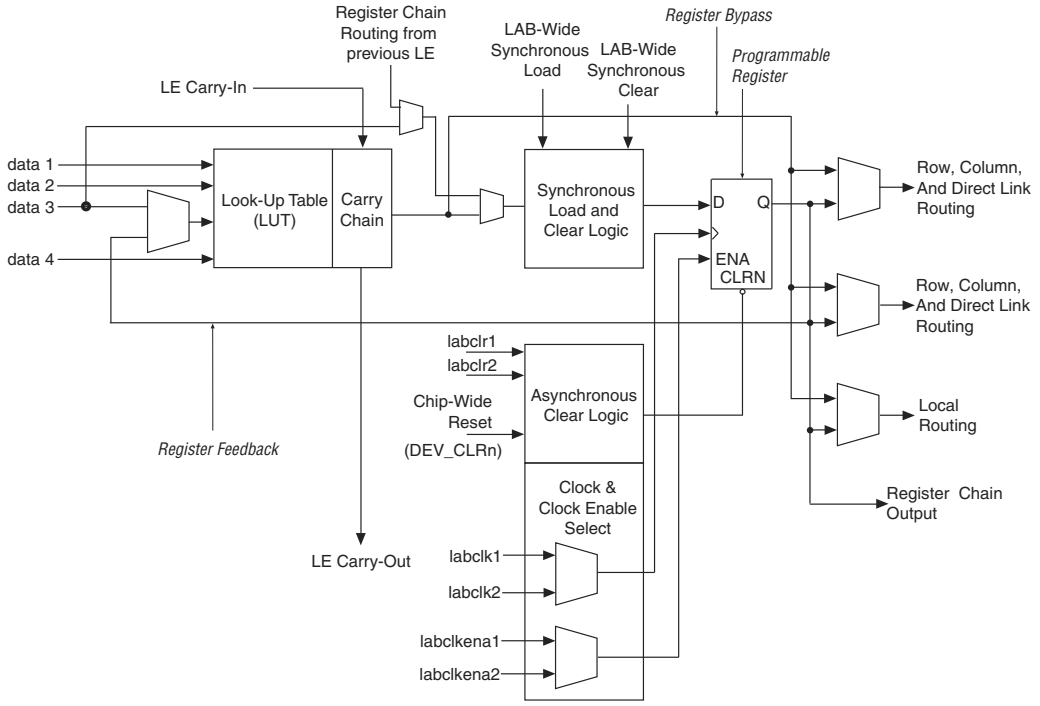
Chapter 9. SEU Mitigation in Cyclone IV Devices
Revised: *May 2013*
Part Number: *CYIV-51009-1.3*

Chapter 10. JTAG Boundary-Scan Testing for Cyclone IV Devices
Revised: *December 2013*
Part Number: *CYIV-51010-1.3*

Chapter 11. Power Requirements for Cyclone IV Devices
Revised: *May 2013*
Part Number: *CYIV-51011-1.3*

Figure 2–1 shows the LEs for Cyclone IV devices.

Figure 2–1. Cyclone IV Device LEs



LE Features

You can configure the programmable register of each LE for D, T, JK, or SR flipflop operation. Each register has data, clock, clock enable, and clear inputs. Signals that use the global clock network, general-purpose I/O pins, or any internal logic can drive the clock and clear control signals of the register. Either general-purpose I/O pins or the internal logic can drive the clock enable. For combinational functions, the LUT output bypasses the register and drives directly to the LE outputs.

Each LE has three outputs that drive the local, row, and column routing resources. The LUT or register output independently drives these three outputs. Two LE outputs drive the column or row and direct link routing connections, while one LE drives the local interconnect resources. This allows the LUT to drive one output while the register drives another output. This feature, called register packing, improves device utilization because the device can use the register and the LUT for unrelated functions. The LAB-wide synchronous load control signal is not available when using register packing. For more information about the synchronous load control signal, refer to "LAB Control Signals" on page 2–6.

The register feedback mode allows the register output to feed back into the LUT of the same LE to ensure that the register is packed with its own fan-out LUT, providing another mechanism for improved fitting. The LE can also drive out registered and unregistered versions of the LUT output.

Power-Up Conditions and Memory Initialization

The M9K memory block outputs of Cyclone IV devices power up to zero (cleared) regardless of whether the output registers are used or bypassed. All M9K memory blocks support initialization using a **.mif**. You can create **.mif**s in the Quartus II software and specify their use using the RAM MegaWizard Plug-In Manager when instantiating memory in your design. Even if memory is pre-initialized (for example, using a **.mif**), it still powers up with its outputs cleared. Only the subsequent read after power up outputs the pre-initialized values.

For more information about **.mif**s, refer to the *RAM Megafunction User Guide* and the *Quartus II Handbook*.

Power Management

The M9K memory block clock enables of Cyclone IV devices allow you to control clocking of each M9K memory block to reduce AC power consumption. Use the `rden` signal to ensure that read operations only occur when necessary. If your design does not require read-during-write, reduce power consumption by deasserting the `rden` signal during write operations or any period when there are no memory operations. The Quartus II software automatically powers down any unused M9K memory blocks to save static power.

Document Revision History

Table 3–6 shows the revision history for this chapter.

Table 3–6. Document Revision History

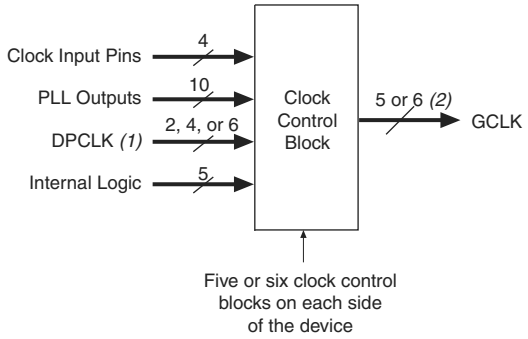
Date	Version	Changes
November 2011	1.1	Updated the “Byte Enable Support” section.
November 2009	1.0	Initial release.

From the clock sources listed above, only two clock input pins, two out of four PLL clock outputs (two clock outputs from either adjacent PLLs), one DPCLK pin, and one source from internal logic can drive into any given clock control block, as shown in Figure 5–1 on page 5–11.

Out of these six inputs to any clock control block, the two clock input pins and two PLL outputs are dynamically selected to feed a GCLK. The clock control block supports static selection of the signal from internal logic.

Figure 5–5 shows a simplified version of the clock control blocks on each side of the Cyclone IV GX device periphery.

Figure 5–5. Clock Control Blocks on Each Side of Cyclone IV GX Device



Notes to Figure 5–5:

(1) The EP4CGX15 device has two DPCLK pins; the EP4CGX22 and EP4CGX30 devices have four DPCLK pins; the EP4CGX50, EP4CGX75, EP4CGX110, and EP4CGX150 devices have six DPCLK pins.

(2) Each clock control block in the EP4CGX15, EP4CGX22, and EP4CGX30 devices can drive five GCLK networks. Each clock control block in the EP4CGX50, EP4CGX75, EP4CGX110, and EP4CGX150 devices can drive six GCLK networks.

The inputs to the five clock control blocks on each side of the Cyclone IV E device must be chosen from among the following clock sources:

- Three or four clock input pins, depending on the specific device
- Five PLL counter outputs
- Two DPCLK pins and two CDPCLK pins from both the left and right sides and four DPCLK pins from both the top and bottom
- Five signals from internal logic

From the clock sources listed above, only two clock input pins, two PLL clock outputs, one DPCLK or CDPCLK pin, and one source from internal logic can drive into any given clock control block, as shown in Figure 5–1 on page 5–11.

Out of these six inputs to any clock control block, the two clock input pins and two PLL outputs are dynamically selected to feed a GCLK. The clock control block supports static selection of the signal from internal logic.

Deterministic Latency Compensation Mode

The deterministic latency mode compensates for the delay of the multipurpose PLLs through the clock network and serializer in Common Public Radio Interface (CPRI) applications. In this mode, the PLL PFD feedback path compensates the latency uncertainty in `Tx dataout` and `Tx clkout` paths relative to the reference clock.

Hardware Features

Cyclone IV PLLs support several features for general-purpose clock management. This section discusses clock multiplication and division implementation, phase shifting implementations, and programmable duty cycles.

Clock Multiplication and Division

Each Cyclone IV PLL provides clock synthesis for PLL output ports using M/(N*post-scale counter) scaling factors. The input clock is divided by a pre-scale factor, N, and is then multiplied by the M feedback factor. The control loop drives the VCO to match f_{IN} (M/N). Each output port has a unique post-scale counter that divides down the high-frequency VCO. For multiple PLL outputs with different frequencies, the VCO value is the least common multiple of the output frequencies that meets its frequency specifications. For example, if output frequencies required from one PLL are 33 and 66 MHz, the Quartus II software sets the VCO to 660 MHz (the least common multiple of 33 and 66 MHz in the VCO range). Then, the post-scale counters scale down the VCO frequency for each output port.

There is one pre-scale counter, N, and one multiply counter, M, per PLL, with a range of 1 to 512 for both M and N. The N counter does not use duty cycle control because the purpose of this counter is only to calculate frequency division. There are five generic post-scale counters per PLL that can feed GCLKs or external clock outputs. These post-scale counters range from 1 to 512 with a 50% duty cycle setting. The post-scale counters range from 1 to 256 with any non-50% duty cycle setting. The sum of the high/low count values chosen for a design selects the divide value for a given counter.

The Quartus II software automatically chooses the appropriate scaling factors according to the input frequency, multiplication, and division values entered into the ALTPLL megafunction.

Phase alignment between output counters is determined using the t_{PLL_PSERR} specification.

Table 6–2 on page 6–7 shows the possible settings for I/O standards with current strength control. These programmable current strength settings are a valuable tool in helping decrease the effects of simultaneously switching outputs (SSO) in conjunction with reducing system noise. The supported settings ensure that the device driver meets the specifications for IOH and IOL of the corresponding I/O standard.

☞ When you use programmable current strength, on-chip series termination (R_S OCT) is not available.

Slew Rate Control

The output buffer for each Cyclone IV I/O pin provides optional programmable output slew-rate control. Table 6–2 on page 6–7 shows the possible slew rate option and the Quartus II default slew rate setting. However, these fast transitions may introduce noise transients in the system. A slower slew rate reduces system noise, but adds a nominal delay to rising and falling edges. Because each I/O pin has an individual slew-rate control, you can specify the slew rate on a pin-by-pin basis. The slew-rate control affects both the rising and falling edges. Slew rate control is available for single-ended I/O standards with current strength of 8 mA or higher.

☞ You cannot use the programmable slew rate feature when using OCT with calibration.

☞ You cannot use the programmable slew rate feature when using the 3.0-V PCI, 3.0-V PCI-X, 3.3-V LVTTL, or 3.3-V LVCMOS I/O standards. Only the fast slew rate (default) setting is available.

Open-Drain Output

Cyclone IV devices provide an optional open-drain (equivalent to an open-collector) output for each I/O pin. This open-drain output enables the device to provide system-level control signals (for example, interrupt and write enable signals) that are asserted by multiple devices in your system.

Bus Hold

Each Cyclone IV device user I/O pin provides an optional bus-hold feature. The bus-hold circuitry holds the signal on an I/O pin at its last-driven state. Because the bus-hold feature holds the last-driven state of the pin until the next input signal is present, an external pull-up or pull-down resistor is not necessary to hold a signal level when the bus is tri-stated.

The bus-hold circuitry also pulls undriven pins away from the input threshold voltage in which noise can cause unintended high-frequency switching. You can select this feature individually for each I/O pin. The bus-hold output drives no higher than V_{CCIO} to prevent overdriving signals.

☞ If you enable the bus-hold feature, the device cannot use the programmable pull-up option. Disable the bus-hold feature when the I/O pin is configured for differential signals. Bus-hold circuitry is not available on dedicated clock pins.

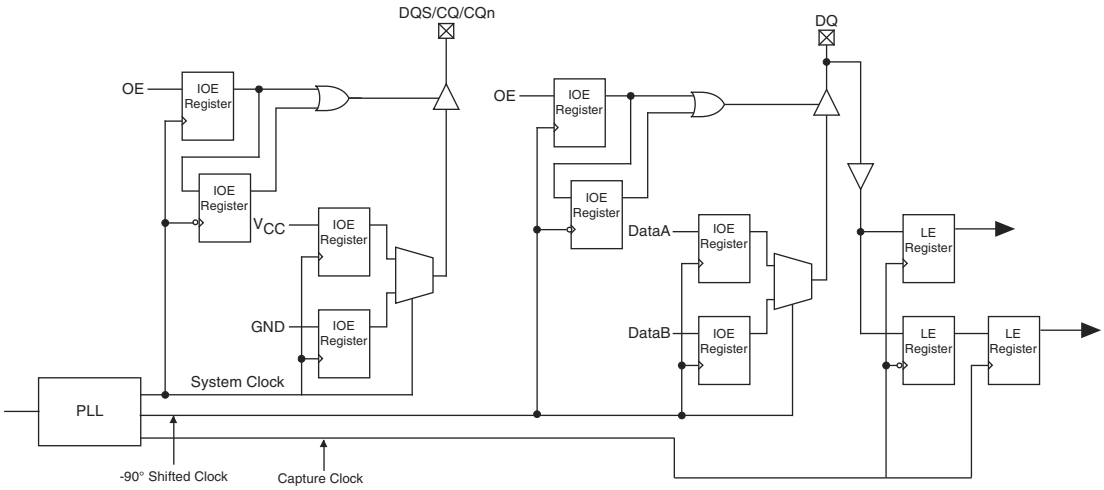
Bus-hold circuitry is only active after configuration. When going into user mode, the bus-hold circuit captures the value on the pin present at the end of configuration.

Table 6–12. Document Revision History (Part 2 of 2)

Date	Version	Changes
February 2010	2.0	■ Added Cyclone IV E devices information for the Quartus II software version 9.1 SP1 release. ■ Updated Table 6–2, Table 6–3, and Table 6–10. ■ Updated "I/O Banks" section. ■ Added Figure 6–9. ■ Updated Figure 6–10 and Figure 6–11. ■ Added Table 6–4, Table 6–6, and Table 6–8.
November 2009	1.0	Initial release.

Figure 7–1 shows the block diagram of a typical external memory interface data path in Cyclone IV devices.

Figure 7–1. Cyclone IV Devices External Memory Data Path *(1)*



Note to Figure 7–1:

(1) All clocks shown here are global clocks.

For more information about implementing complete external memory interfaces, refer to the *External Memory Interface Handbook*.

Cyclone IV Devices Memory Interfaces Pin Support

Cyclone IV devices use data (DQ), data strobe (DQS), clock, command, and address pins to interface with external memory. Some memory interfaces use the data mask (DM) or byte write select (BWS#) pins to enable data masking. This section describes how Cyclone IV devices support all these different pins.

For more information about pin utilization, refer to *Volume 2: Device, Pin, and Board Layout Guidelines* of the *External Memory Interface Handbook*.

Data and Data Clock/Strobe Pins

Cyclone IV data pins for external memory interfaces are called D for write data, Q for read data, or DQ for shared read and write data pins. The read-data strobes or read clocks are called DQS pins. Cyclone IV devices support both bidirectional data strobes and unidirectional read clocks. Depending on the external memory standard, the DQ and DQS are bidirectional signals (in DDR2 and DDR SDRAM) or unidirectional signals (in QDR II SRAM). Connect the bidirectional DQ data signals to the same Cyclone IV devices DQ pins. For unidirectional D or Q signals, connect the read-data signals to a group of DQ pins and the write-data signals to a different group of DQ pins.

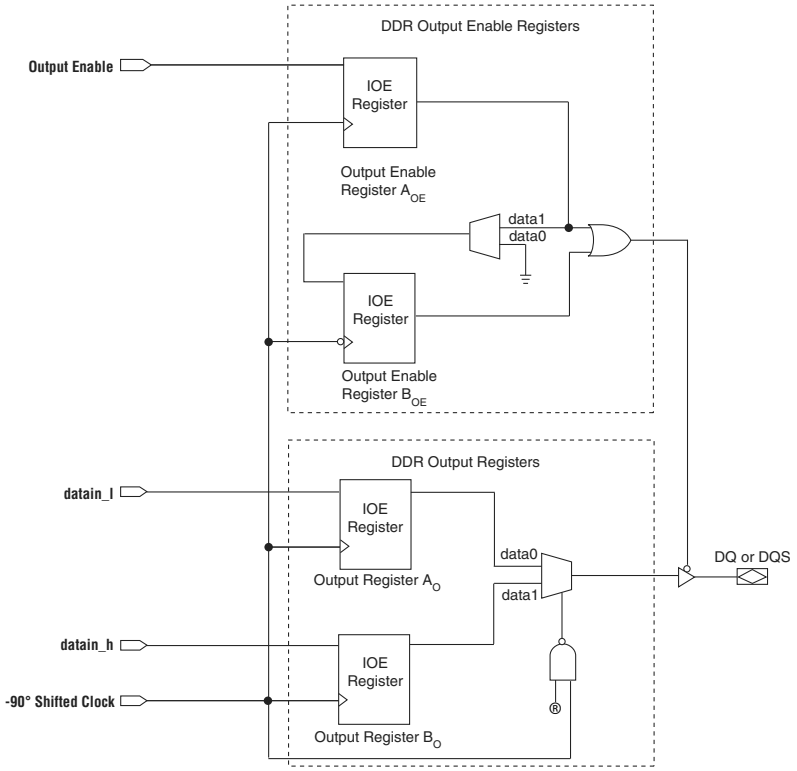
In QDR II SRAM, the Q read-data group must be placed at a different V_{REF} bank location from the D write-data group, command, or address pins.

DDR Output Registers

A dedicated write DDIO block is implemented in the DDR output and output enable paths.

Figure 7–8 shows how a Cyclone IV dedicated write DDIO block is implemented in the I/O element (IOE) registers.

Figure 7–8. Cyclone IV Dedicated Write DDIO



The two DDR output registers are located in the I/O element (IOE) block. Two serial data streams routed through `datain_l` and `datain_h`, are fed into two registers, `output register Ao` and `output register Bo`, respectively, on the same clock edge. The output from `output register Ao` is captured on the falling edge of the clock, while the output from `output register Bo` is captured on the rising edge of the clock. The registered outputs are multiplexed by the common clock to drive the DDR output pin at twice the data rate.

The DDR output enable path has a similar structure to the DDR output path in the IOE block. The second output enable register provides the write preamble for the `DQS` strobe in DDR external memory interfaces. This active-low output enable register extends the high-impedance state of the pin by half a clock cycle to provide the external memory's `DQS` write preamble time specification.

For more information about Cyclone IV IOE registers, refer to the *Cyclone IV Device I/O Features* chapter.

Table 8–2. Uncompressed Raw Binary File (.rbf) Sizes for Cyclone IV Devices (Part 2 of 2)

Device		Data Size (bits)
Cyclone IV GX	EP4CGX15	3,805,568
	EP4CGX22	7,600,040
	EP4CGX30	7,600,040
		22,010,888 (1)
	EP4CGX50	22,010,888
	EP4CGX75	22,010,888
	EP4CGX110	39,425,016
	EP4CGX150	39,425,016

Note to Table 8–2:

(1) Only for the F484 package.

Use the data in Table 8–2 to estimate the file size before design compilation. Different configuration file formats, such as Hexadecimal (**.hex**) or Tabular Text File (**.ttf**) formats, have different file sizes. However, for any specific version of the Quartus II software, any design targeted for the same device has the same uncompressed configuration file size. If you use compression, the file size varies after each compilation, because the compression ratio depends on the design.

For more information about setting device configuration options or creating configuration files, refer to the *Software Settings* section in volume 2 of the *Configuration Handbook*.

Configuration and JTAG Pin I/O Requirements

Cyclone IV devices are manufactured using the TSMC 60-nm low-k dielectric process. Although Cyclone IV devices use TSMC 2.5-V transistor technology in the I/O buffers, the devices are compatible and able to interface with 2.5, 3.0, and 3.3-V configuration voltage standards by following specific requirements.

All I/O inputs must maintain a maximum AC voltage of 4.1 V. When using a serial configuration device in an AS configuration scheme, you must connect a 25-Ω series resistor for the DATA[0] pin. When cascading the Cyclone IV device family in a multi-device configuration for AS, AP, FPP, and PS configuration schemes, you must connect the repeater buffers between the master and slave devices for the DATA and DCLK pins. When using the JTAG configuration scheme in a multi-device configuration, connect 25-Ω resistors on both ends of the TDO-TDI path if the TDO output driver is a non-Cyclone IV device.

The output resistance of the repeater buffers and the TDO path for all cases must fit the maximum overshoot equation shown in Equation 8–1.

Equation 8–1. (1)

$$0.8Z_O \leq R_E \leq 1.8Z_O$$

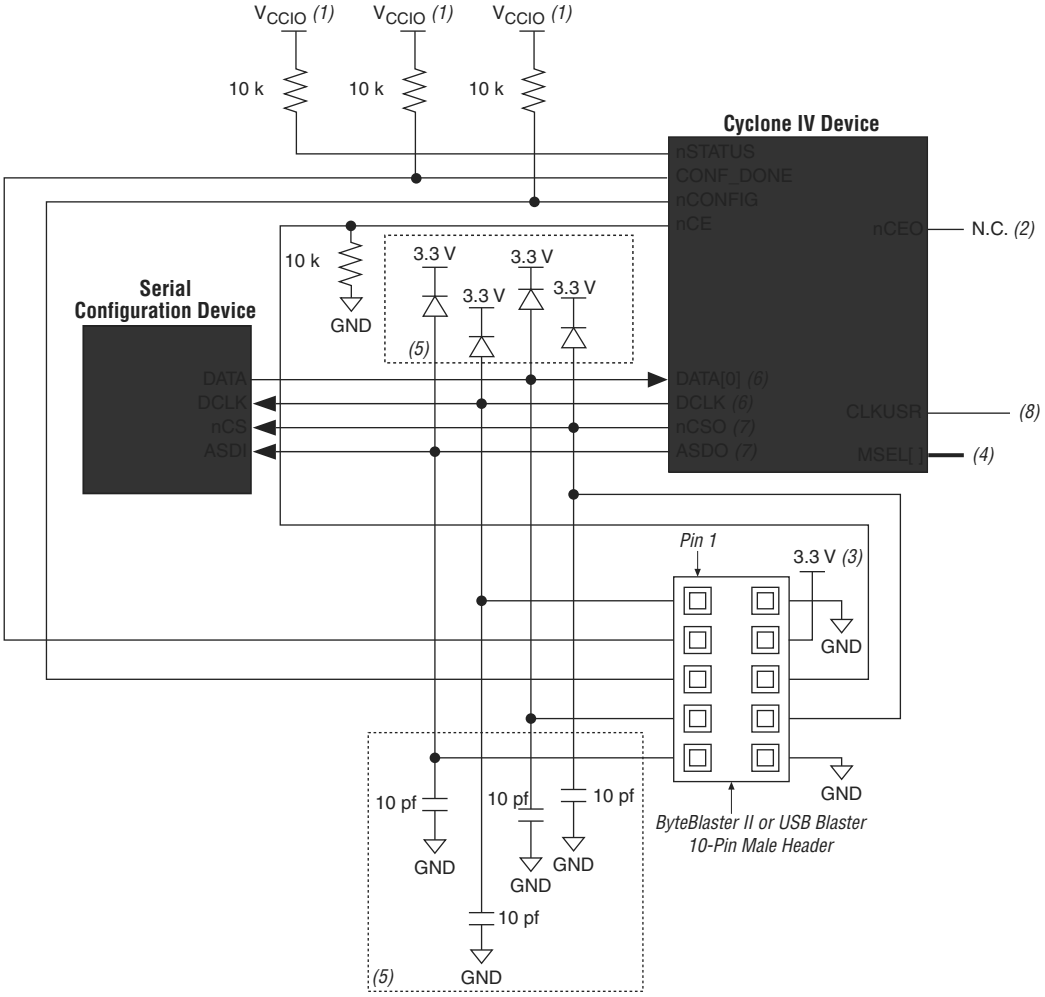
Note to Equation 8–1:

(1) Z_O is the transmission line impedance and R_E is the equivalent resistance of the output buffer.

For more information about the USB-Blaster download cable, refer to the *USB-Blaster Download Cable User Guide*. For more information about the ByteBlaster II download cable, refer to the *ByteBlaster II Download Cable User Guide*.

Figure 8–6 shows the download cable connections to the serial configuration device.

Figure 8–6. In-System Programming of Serial Configuration Devices



Notes to Figure 8–6:

(1) Connect these pull-up resistors to the V_{CCIO} supply of the bank in which the pin resides.

(2) The nCEO pin is left unconnected or used as a user I/O pin when it does not feed the nCE pin of another device.

(3) Power up the V_{CC} of the ByteBlaster II or USB-Blaster download cable with the 3.3-V supply.

(4) The MSEL pin settings vary for different configuration voltage standards and POR time. To connect the MSEL pins, refer to Table 8–3 on page 8–8, Table 8–4 on page 8–8, and Table 8–5 on page 8–9. Connect the MSEL pins directly to V_{CCA} or GND.

(5) The diodes and capacitors must be placed as close as possible to the Cyclone IV device. You must ensure that the diodes and capacitors maintain a maximum AC voltage of 4.1 V. The external diodes and capacitors are required to prevent damage to the Cyclone IV device AS configuration input pins due to possible overshoot when programming the serial configuration device with a download cable. Altera recommends using the Schottky diode, which has a relatively lower forward diode voltage (VF) than the switching and Zener diodes, for effective voltage clamping.

(6) When cascading Cyclone IV devices in a multi-device AS configuration, connect the repeater buffers between the master and slave devices for DATA[0] and DCLK. All I/O inputs must maintain a maximum AC voltage of 4.1 V. The output resistance of the repeater buffers must fit the maximum overshoot equation outlined in "Configuration and JTAG Pin I/O Requirements" on page 8–5.

(7) These pins are dual-purpose I/O pins. The nCSO pin functions as FLASH_nCE pin in AP mode. The ASDO pin functions as DATA[1] pin in AP and FPP modes.

(8) Only Cyclone IV GX devices have an option to select CLKUSR (40 MHz maximum) as the external clock source for DCLK.

There are no series resistors required in AP configuration mode for Cyclone IV E devices when using the Micron flash at 2.5-, 3.0-, and 3.3-V I/O standard. The output buffer of the Micron P30 IBIS model does not overshoot above 4.1 V. Thus, series resistors are not required for the 2.5-, 3.0-, and 3.3-V AP configuration option. However, if there are any other devices sharing the same flash I/Os with Cyclone IV E devices, all shared pins are still subject to the 4.1-V limit and may require series resistors.

Default read mode of the supported parallel flash memory and all writes to the parallel flash memory are asynchronous. Both the parallel flash families support a synchronous read mode, with data supplied on the positive edge of DCLK.

The serial clock (DCLK) generated by Cyclone IV E devices controls the entire configuration cycle and provides timing for the parallel interface.

Multi-Device AP Configuration

You can configure multiple Cyclone IV E devices using a single parallel flash. You can cascade multiple Cyclone IV E devices using the chip-enable (nCE) and chip-enable-out (nCEO) pins. The first device in the chain must have its nCE pin connected to GND. You must connect its nCEO pin to the nCE pin of the next device in the chain. Use an external 10-kΩ pull-up resistor to pull the nCEO signal high to its V_{CCIO} level to help the internal weak pull-up resistor. When the first device captures all its configuration data from the bitstream, it drives the nCEO pin low, enabling the next device in the chain. You can leave the nCEO pin of the last device unconnected or use it as a user I/O pin after configuration if the last device in the chain is a Cyclone IV E device. The nCONFIG, nSTATUS, CONF_DONE, DCLK, DATA[15..8], and DATA[7..0] pins of each device in the chain are connected (Figure 8–8 on page 8–26 and Figure 8–9 on page 8–27).

The first Cyclone IV E device in the chain, as shown in Figure 8–8 on page 8–26 and Figure 8–9 on page 8–27, is the configuration master device and controls the configuration of the entire chain. You must connect its MSEL pins to select the AP configuration scheme. The remaining Cyclone IV E devices are used as configuration slaves. You must connect their MSEL pins to select the FPP configuration scheme. Any other Altera device that supports FPP configuration can also be part of the chain as a configuration slave.

The following are the configurations for the DATA[15..0] bus in a multi-device AP configuration:

- Byte-wide multi-device AP configuration
- Word-wide multi-device AP configuration

9. SEU Mitigation in Cyclone IV Devices

CYIV-51009-1.3

This chapter describes the cyclical redundancy check (CRC) error detection feature in user mode and how to recover from soft errors.

☞ Configuration error detection is supported in all Cyclone® IV devices including Cyclone IV GX devices, Cyclone IV E devices with 1.0-V core voltage, and Cyclone IV E devices with 1.2-V core voltage. However, user mode error detection is only supported in Cyclone IV GX devices and Cyclone IV E devices with 1.2-V core voltage.

Dedicated circuitry built into Cyclone IV devices consists of a CRC error detection feature that can optionally check for a single-event upset (SEU) continuously and automatically.

In critical applications used in the fields of avionics, telecommunications, system control, medical, and military applications, it is important to be able to:

- Confirm the accuracy of the configuration data stored in an FPGA device
- Alert the system to an occurrence of a configuration error

Using the CRC error detection feature for Cyclone IV devices does not impact fitting or performance.

This chapter contains the following sections:

- "Configuration Error Detection" on page 9–1
- "User Mode Error Detection" on page 9–2
- "Automated SEU Detection" on page 9–3
- "CRC_ERROR Pin" on page 9–3
- "Error Detection Block" on page 9–4
- "Error Detection Timing" on page 9–5
- "Software Support" on page 9–6
- "Recovering from CRC Errors" on page 9–9

Configuration Error Detection

☞ Configuration error detection is available in all Cyclone IV devices including Cyclone IV GX devices, Cyclone IV E devices with 1.0-V core voltage, and Cyclone IV E devices with 1.2-V core voltage.

Transmitter Channel Datapath

The following sections describe the Cyclone IV GX transmitter channel datapath architecture as shown in Figure 1–3:

- TX Phase Compensation FIFO
- Byte Serializer
- 8B/10B Encoder
- Serializer
- Transmitter Output Buffer

TX Phase Compensation FIFO

The TX phase compensation FIFO compensates for the phase difference between the low-speed parallel clock and the FPGA fabric interface clock, when interfacing the transmitter channel to the FPGA fabric (directly or through the PIPE and PCIe hard IP). The FIFO is four words deep, with latency between two to three parallel clock cycles. Figure 1–4 shows the TX phase compensation FIFO block diagram.

Figure 1–4. TX Phase Compensation FIFO Block Diagram

Note to Figure 1–4:

(1) The x refers to the supported 8-, 10-, 16-, or 20-bits transceiver channel width.

The FIFO can operate in registered mode, contributing to only one parallel clock cycle of latency in Deterministic Latency functional mode. For more information, refer to "Deterministic Latency Mode" on page 1–73.

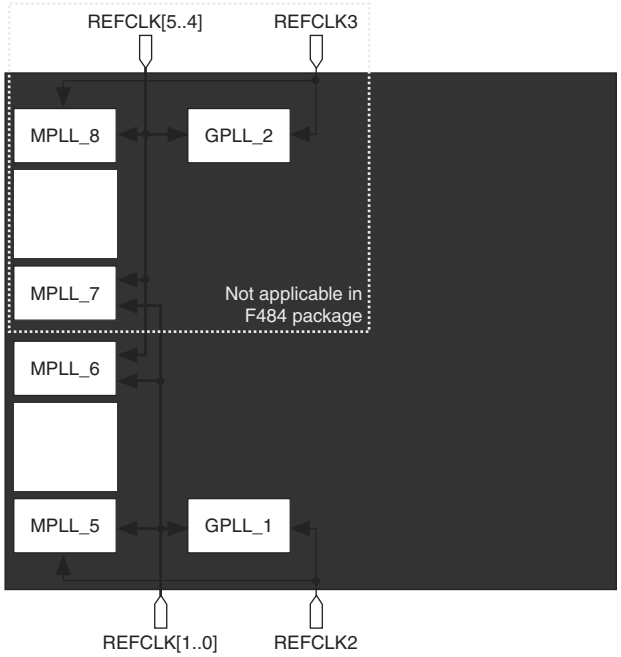
For more information about FIFO clocking, refer to "FPGA Fabric-Transceiver Interface Clocking" on page 1–43.

Byte Serializer

The byte serializer divides the input datapath width by two to allow transmitter channel operation at higher data rates while meeting the maximum FPGA fabric frequency limit. This module is required in configurations that exceed the maximum FPGA fabric-transceiver interface clock frequency limit and optional in configurations that do not.

For the FPGA fabric-transceiver interface frequency specifications, refer to the *Cyclone IV Device Data Sheet*.

Figure 1–26. PLL Input Reference Clocks in Transceiver Operation for F484 and Larger Packages (1), (2), (3)



Notes to Figure 1–26:

(1) The REFCLK2 and REFCLK3 pins are dual-purpose CLKIO, REFCLK, or DIFFCLK pins that reside in banks 3A and 8A respectively.

(2) The REFCLK[1..0] and REFCLK[5..4] pins are dual-purpose differential REFCLK or DIFFCLK pins that reside in banks 3B and 8B respectively. These clock input pins do not have access to the clock control blocks and GCLK networks. For more details, refer to the *Clock Networks and PLLs in Cyclone IV Devices* chapter.

(3) Using any clock input pins other than the designated REFCLK pins as shown here to drive the MPLLs and GPLLs may have reduced jitter performance.

The input reference clocks reside in banks 3A, 3B, 8A, and 8B have dedicated $V_{CC\_CLKIN3A}$, $V_{CC\_CLKIN3B}$, $V_{CC\_CLKIN8A}$, and $V_{CC\_CLKIN8B}$ power supplies separately in their respective I/O banks to avoid the different power level requirements in the same bank for general purpose I/Os (GPIOs). Table 1–6 lists the supported I/O standard for the REFCLK pins.

Table 1–6. REFCLK I/O Standard Support

I/O Standard	HSSI Protocol	Coupling	Termination	VCC_CLKIN Level		I/O Pin Type		
				Input	Output	Column I/O	Row I/O	Supported Banks
LVDS	ALL	Differential AC (Needs off-chip resistor to restore V_{CM})	Off-chip	2.5 V	Not Supported	Yes	No	3A, 3B, 8A, 8B
LVPECL	ALL		Off-chip	2.5 V	Not Supported	Yes	No	3A, 3B, 8A, 8B
1.2 V, 1.5 V, 3.3 V PCML	ALL		Off-chip	2.5 V	Not Supported	Yes	No	3A, 3B, 8A, 8B
	ALL		Off-chip	2.5 V	Not Supported	Yes	No	3A, 3B, 8A, 8B
	ALL		Off-chip	2.5 V	Not Supported	Yes	No	3A, 3B, 8A, 8B
HCSL	PCIe	Differential DC	Off-chip	2.5 V	Not Supported	Yes	No	3A, 3B, 8A, 8B

Bonded Channel Configuration

In bonded channel configuration, the low-speed clock for the bonded channels share a common bonded clock path that reduces clock skew between the bonded channels. The phase compensation FIFOs in bonded channels share a set of pointers and control logic that results in equal FIFO latency between the bonded channels. These features collectively result in lower channel-to-channel skew when implementing multi-channel serial interface in bonded channel configuration.

In a transceiver block, the high-speed clock for each bonded channels is distributed independently from one of the two multipurpose PLLs directly adjacent to the block. The low-speed clock for bonded channels is distributed from a common bonded clock path that selects from one of the two multipurpose PLLs directly adjacent to the block. Transceiver channels for devices in F484 and larger packages support additional clocking flexibility for ×2 bonded channels. In these packages, the ×2 bonded channels support high-speed and low-speed bonded clock distribution from PLLs beyond the two multipurpose PLLs directly adjacent to the block. Table 1–10 lists the high- and low-speed clock sources for the bonded channels.

Table 1–10. High- and Low-Speed Clock Sources for Bonded Channels in Bonded Channel Configuration

Package	Transceiver Block	Bonded Channels	High- and Low-Speed Clocks Source	
			Option 1	Option 2
F324 and smaller	GXBL0	×2 in channels 0, 1 ×4 in all channels	MPLL_1	MPLL_2
F484 and larger	GXBL0	×2 in channels 0, 1	MPLL_5/ GPLL_1	MPLL_6
		×4 in all channels	MPLL_5	MPLL_6
	GXBL1 (1)	×2 in channels 0, 1	MPLL_7/ MPLL_6	MPLL_8
		×4 in all channels	MPLL_7	MPLL_8

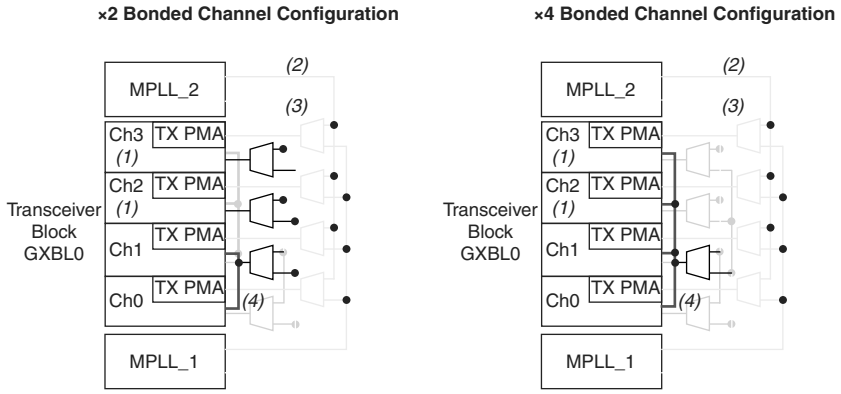
Note to Table 1–10:

(1) GXBL1 is not available for transceivers in F484 package.

When implementing ×2 bonded channel configuration in a transceiver block, remaining channels 2 and 3 are available to implement other non-bonded channel configuration.

Figure 1–36 and Figure 1–37 show the independent high-speed clock and bonded low-speed clock distributions for transceivers in F324 and smaller packages, and in F484 and larger packages in bonded (×2 and ×4) channel configuration.

Figure 1–36. Clock Distribution in Bonded (×2 and ×4) Channel Configuration for Transceivers in F324 and Smaller Packages.

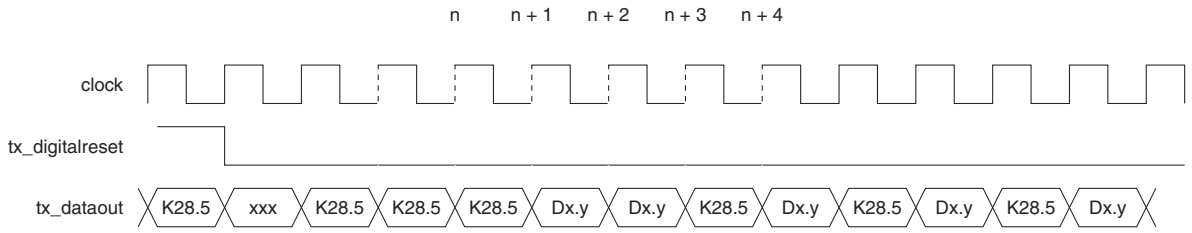


Notes to Figure 1–36:

(1) Transceiver channels 2 and 3 are not available for devices in F169 and smaller packages.
(2) High-speed clock.
(3) Low-speed clock.
(4) Bonded common low-speed clock path.

Figure 1–57 shows an example of even numbers of /Dx.y/ between the last automatically sent /K28.5/ and the first user-sent /K28.5/. The first user-sent /K28.5/ code group received at an odd code group boundary in cycle $n + 3$ takes the receiver synchronization state machine in Loss-of-Sync state. The first synchronization ordered-set /K28.5/Dx.y/ in cycles $n + 3$ and $n + 4$ is discounted and three additional ordered sets are required for successful synchronization.

Figure 1–57. Example of Reset Condition in GIGE Mode



Running Disparity Preservation with Idle Ordered Set

During idle ordered sets transmission in GIGE mode, the transmitter ensures a negative running disparity at the end of an idle ordered set. Any /Dx.y/, except for /D21.5/ (part of /C1/ ordered set) or /D2.2/ (part of /C2/ ordered set) following a /K28.5/ is automatically replaced with either of the following:

- A /D5.6/ (/I1/ ordered set) if the running disparity before /K28.5/ is positive
- A /D16.2/ (/I2/ ordered set) if the running disparity before /K28.5/ is negative

Lane Synchronization

In GIGE mode, the word aligner is configured in automatic synchronization state machine mode that complies with the IEEE P802.3ae standard. A synchronization ordered set is a /K28.5/ code group followed by an odd number of valid /Dx.y/ code groups. Table 1–19 lists the synchronization state machine parameters that implements the GbE-compliant synchronization.

Table 1–19. Synchronization State Machine Parameters (1)

Parameter	Value
Number of valid synchronization ordered sets received to achieve synchronization	3
Number of erroneous code groups received to lose synchronization	4
Number of continuous good code groups received to reduce the error count by one	4

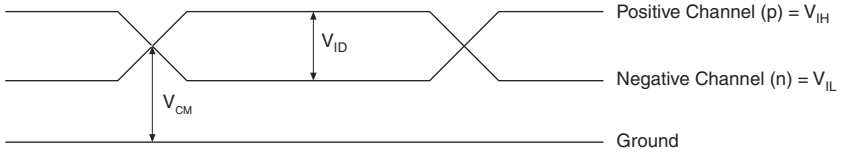
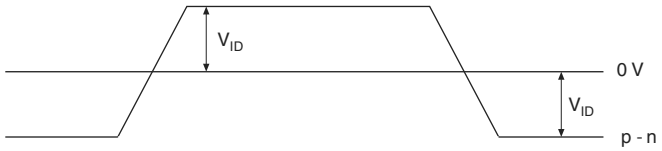
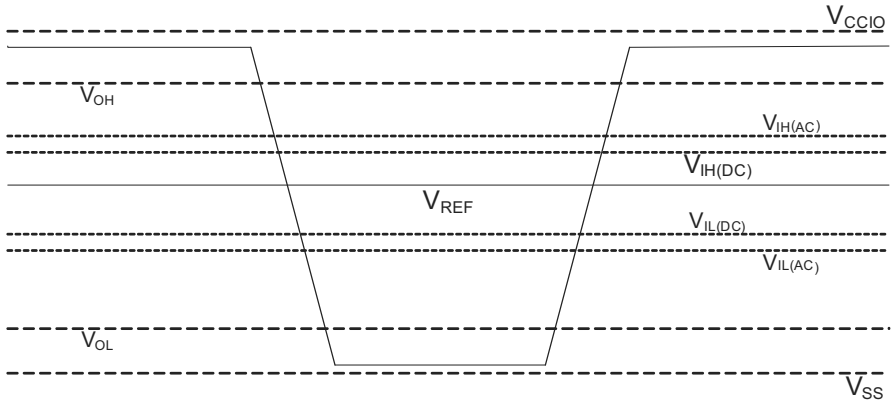
Note to Table 1–19:

(1) The word aligner supports 7-bit and 10-bit pattern lengths in GIGE mode.

Table 1–27. Receiver Ports in ALTGX Megafunction for Cyclone IV GX (Part 2 of 3)

Block	Port Name	Input/ Output	Clock Domain	Description
RX PCS	rx_rmfifofull	Output	Synchronous to tx_clkout (non-bonded modes) or coreclkout (bonded modes)	Rate match FIFO full status indicator. ■ A high level indicates the rate match FIFO is full. ■ Driven for a minimum of two serial clock cycles in configurations without a byte serializer and a minimum of three recovered clock cycles in configurations with a byte serializer.
	rx_rmfifoempty	Output	Synchronous to tx_clkout (non-bonded modes) or coreclkout (bonded modes)	Rate match FIFO empty status indicator. ■ A high level indicates the rate match FIFO is empty. ■ Driven for a minimum of two serial clock cycles in configurations without a byte serializer and a minimum of three recovered clock cycles in configurations with a byte serializer.
	rx_ctrldetect	Output	Synchronous to tx_clkout (non-bonded modes) or coreclkout (bonded modes)	8B/10B decoder control or data identifier. ■ A high level indicates received code group is a /Kx.y/ control code group. ■ A low level indicates received code group is a /Dx.y/ data code group.
	rx_errdetect	Output	Synchronous to tx_clkout (non-bonded modes) or coreclkout (bonded modes)	8B/10B code group violation or disparity error indicator. ■ A high level indicates that a code group violation or disparity error was detected on the associated received code group. ■ Use with the rx_disperr signal to differentiate between a code group violation or a disparity error as follows: [rx_errdetect:rx_disperr] ■ 2'b00—no error ■ 2'b10—code group violation ■ 2'b11—disparity error or both
	rx_disperr	Output	Synchronous to tx_clkout (non-bonded modes) or coreclkout (bonded modes)	8B/10B disparity error indicator. ■ A high level indicates that a disparity error was detected on the associated received code group.
	rx_runningdisp	Output	Synchronous to tx_clkout (non-bonded modes) or coreclkout (bonded modes)	8B/10B current running disparity indicator. ■ A high level indicates a positive current running disparity at the end of the decoded byte ■ A low level indicates a negative current running disparity at the end of the decoded byte
	rx_enabyteord	Input	Asynchronous signal	Enable byte ordering control ■ A low-to-high transition triggers the byte ordering block to restart byte ordering operation.
	rx_byteorder alignstatus	Output	Synchronous to tx_clkout (non-bonded modes) or coreclkout (bonded modes)	Byte ordering status indicator. ■ A high level indicates that the byte ordering block has detected the programmed byte ordering pattern in the least significant byte of the received data from the byte deserializer.
	rx_dataout	Output	Synchronous to tx_clkout (non-bonded modes) or coreclkout (bonded modes)	Parallel data output from the receiver to the FPGA fabric. ■ Bus width depends on channel width multiplied by number of channels per instance.

Table 1–46. Glossary (Part 3 of 5)

Letter	Term	Definitions
R	R_L	Receiver differential input discrete resistor (external to Cyclone IV devices).
	Receiver Input Waveform	Receiver input waveform for LVDS and LVPECL differential standards: **Single-Ended Waveform**  **Differential Waveform (Mathematical Function of Positive & Negative Channel)** 
	Receiver input skew margin (RSKM)	High-speed I/O block: The total margin left after accounting for the sampling window and TCCS. RSKM = (TUI – SW – TCCS) / 2.
S	Single-ended voltage-referenced I/O Standard	 The JEDEC standard for SSTI and HSTL I/O standards defines both the AC and DC input signal values. The AC values indicate the voltage levels at which the receiver must meet its timing specifications. The DC values indicate the voltage levels at which the final logic state of the receiver is unambiguously defined. After the receiver input crosses the AC value, the receiver changes to the new logic state. The new logic state is then maintained as long as the input stays beyond the DC threshold. This approach is intended to provide predictable receiver timing in the presence of input waveform *ringing*.
	SW (Sampling Window)	High-speed I/O block: The period of time during which the data must be valid to capture it correctly. The setup and hold times determine the ideal strobe position in the sampling window.